

Capacitance Values

Part Number	pF Pin 1,8-6,7 / 4,5-6,7 Tip-Ground, Ring-Ground		pF Pin 1,8-4,5 Tip-Ring	
	MIN	MAX	MIN	MAX
P0641DF-1E	40	90	20	45
P0721DF-1E	35	85	20	45
P0901DF-1E	30	80	20	40
P0991DF-1E	25	75	15	35
P1001DF-1E	25	75	15	35
P1101DF-1E	25	70	15	30
P1301DF-1E	20	70	15	30
P1701DF-1E	20	70	15	30

Note: Off-state capacitance (C_o) is measured at 1 MHz with a 2V bias

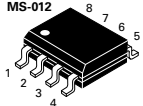
Surge Ratings

Series	I_{PP}				I_{TSM} 600V _{RMS} 1s	di/dt
	2/10	1.2/50 - 8/20	10/700 - 5/310	10/1000	A min	
F	120	100	50	30	1	500

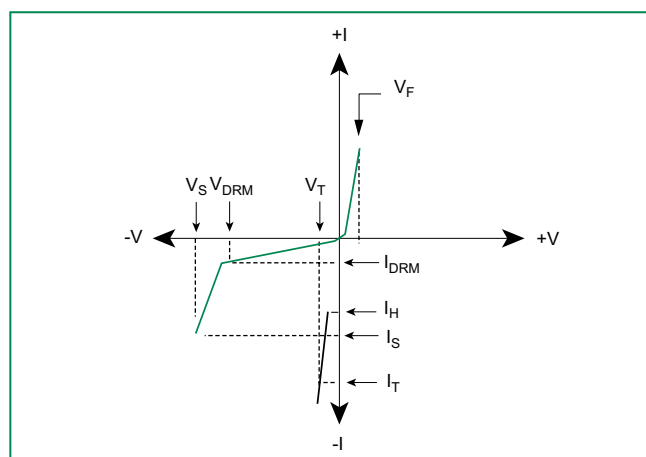
Notes:

- Peak pulse current rating (I_{pp}) is repetitive and guaranteed for the life of the product that is in thermal equilibrium.
- I_{pp} ratings applicable over temperature range of -40°C to +85°C
- The component must initially be in thermal equilibrium with -40°C ≤ T_J ≤ +150°C

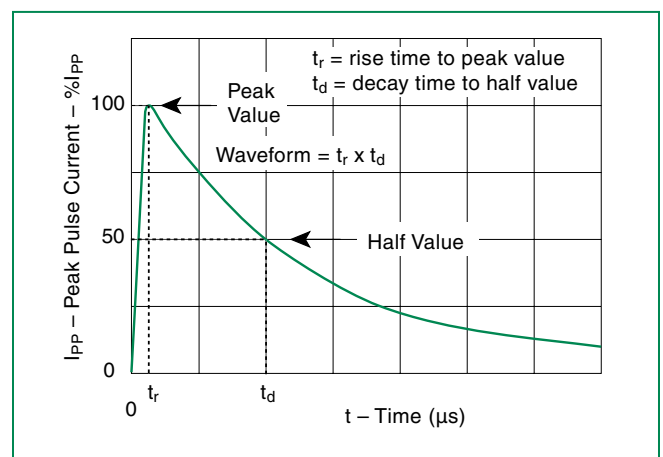
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	120	°C/W

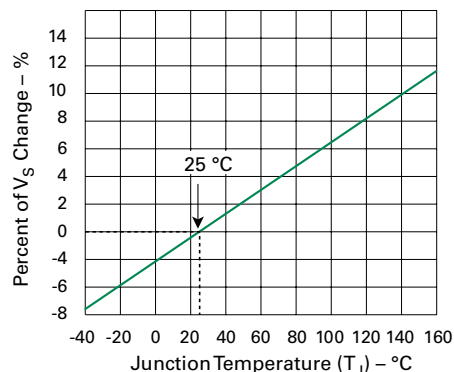
V-I Characteristics



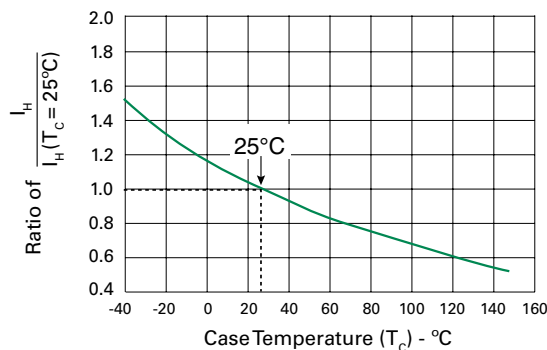
$t_r \times t_d$ Pulse Waveform



Normalized V_s Change vs. Junction Temperature

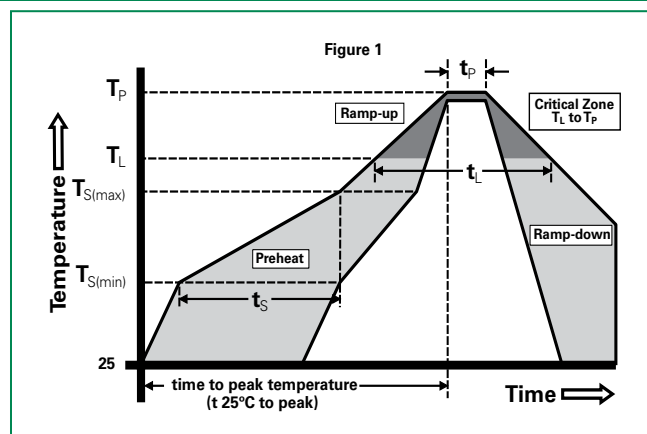


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	- Temperature Min ($T_{s(min)}$)	+150°C
	- Temperature Max ($T_{s(max)}$)	+200°C
	- Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	- Temperature (T_L) (Liquidus)	+217°C
	- Temperature (t_l)	60-150 secs.
PeakTemp (T_p)		+260(+0/-5)°C
Time within 5°C of actual PeakTemp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to PeakTemp (T_p)		8 min. Max.
Do not exceed		+260°C



Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL Recognized compound meeting flammability rating V-0

Additional Information



Datasheet



Resources



Samples

Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} (V_{DC}) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

Dimension	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.053	0.069	1.35	1.75
A1	0.004	0.010	0.10	0.25
A2	0.043	0.065	1.25	1.65
B	0.012	0.020	0.31	0.51
C	0.007	0.010	0.17	0.25
D	0.189	0.197	4.80	5.00
E	0.228	0.244	5.80	6.20
E1	0.150	0.157	3.80	4.00
e	0.050 BSC*		1.27 BSC*	
L	0.016	0.050	0.40	1.27

Pxxx 1 DF -1E

TYPE — **P: SiDACtor**

MEDIAN VOLTAGE —

CONSTRUCTION VARIABLE —

SINGLE ENHANCED —

I_{pp} RATING —

PACKAGE TYPE —

XXXXXF1E
XXXXX

Part Number Code
(Refer to Electrical Characteristics Table)

Date Code

Package Type	Description	Quantity	Added Suffix	Industry Standard
D	MS-012 SMT 8-pin SOIC Tape and Reel Pack	2500	N/A	EIA-481-D

The technical drawing consists of three main views of a carrier tape:

- Top View:** Shows the layout of five pockets. Key dimensions include:
 - Pocket width: 8.0 (.315)
 - Distance between pocket centers: 4.0 (.158)
 - Distance from edge to first pocket center: 2.0 (.079)
 - Distance between mounting holes: 1.55 (.061)
 - Mounting hole diameter: 0.8 (0.03) MIN.
 - Total length shown: 12.0 (.472)
 - Carrier Tape Embossment location: 6.4 (.252) from left edge
 - Minimum distance between embossments: 1.50 (.059) MIN.
 - Direction of Feed arrow pointing right.
- Side View:** Shows the profile of the tape with a height dimension of 0.49 (12.4).
- End View:** Shows the cross-section of the tape with a thickness dimension of 0.016 (0.0016).

A note states: "Dimensions are in inches (and millimeters)." A large arrow indicates the "Direction of Feed".

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